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MICROELECTRONIC PACKAGES WITH LEADFRAMES, INCLUDING
LEADFRAMES CONFIGURED FOR STACKED DIE PACKAGES, AND
ASSOCIATED SYSTEMS AND METHODS

ABSTRACT OF THE DISCLOSURE

Microelectronic packages with leadframes, including leadframes configured for stacked die packages, and associated systems and methods are disclosed. A system in accordance with one embodiment includes a support member having first package bond sites electrically coupled to leadframe bond sites. A microelectronic die can be carried by the support member and electrically coupled to the first packaged bond sites. A leadframe can be attached to the leadframe bond sites so as to extend adjacent to the microelectronic die, with the die positioned between the leadframe and the support member. The leadframe can include second package bond sites facing away from the first package bond sites. An encapsulant can at least partially surround the leadframe and the microelectronic die, with the first and second package bond sites accessible from outside the encapsulant.

Figure : 1